

AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph beginning on page 4, line 12 and ending on page 4, line 22 with the following amended paragraph marked up to show changes made relative to the immediate prior version:

In some embodiments the microchannel member 24 may be a heat spreader, such as an integrated heat spreader (~~HHS~~) (IHS) formed of copper or aluminum, which may be provided in accordance with conventional practices except for the presence of the grooves 28. In other embodiments, the member 24 may not be a heat spreader, but may still be formed of copper or aluminum, or alternatively of silicon. The grooves 28 may be formed in the member 24 by a lithographic process or by micro-machining. Bonding of the member 24 to the rear surface 22 of the IC die 10 may be with gold or solder or by another suitable technique such as thermal compression bonding. Noting again that the drawings are not to scale, the member 24 (whether or not it is a heat spreader) may be substantially thicker than the height of the microchannels 30, and the microchannels may be much narrower than suggested by the drawings.